# EVERLIGHT ELECTRONICS CO.,LTD.

#### **Technical Data Sheet**

## 0603 Package Chip LED (0.6 mm Height)

#### 19-213UYC/S530-XX/TR8

#### **Features**

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS complaint Version.

#### **Descriptions**

- The 19-213 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

#### **Applications**

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

#### **Device Selection Guide**

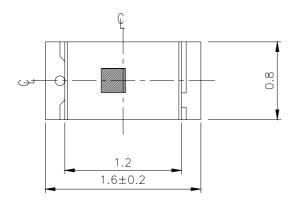
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Part No.	Material	Emitted Color	Lens Color
19-213UYC/S530-XX/TR8	AlGaInP	Brilliant Yellow	Water Clear

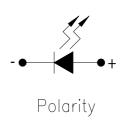


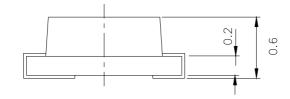
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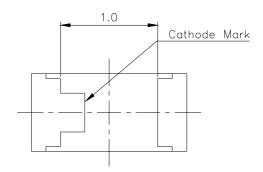
#### **Package Outline Dimensions**

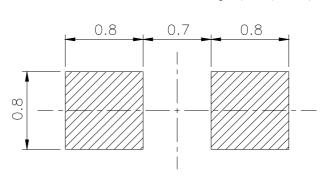






For reflow soldering (Propose)





**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm, Unit = mm



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## 19-213UYC/S530-XX/TR8

#### **Absolute Maximum Ratings (Ta=25°C)**

Parameter	Symbol	Rating	Unit	
Reverse Voltage	$V_R$	5	V	
Forward Current	IF	25	mA	
Operating Temperature	Topr	-40 ~ +85	$^{\circ}$	
Storage Temperature	Tstg	-40~ +90	$^{\circ}$	
Electrostatic Discharge(HBM)	ESD	2000	V	
Power Dissipation	Pd	60	mW	
Peak Forward Current (Duty 1/10 @1KHz)	IFP	60	mA	
Soldering Temperature	Tsol	Reflow Soldering: 260 °C for 10 sec.  Hand Soldering: 350 °C for 3 sec.		

## **Electro-Optical Characteristics (Ta=25°C)**

Parameter	Symbol	*Chip Rank	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity		A2	16	39			
		A3	36	57			
	Iv	A4	52	78		mcd	
		A5	62	98			
		A6	78	114			
Viewing Angle	2 \theta 1/2			120		deg	I <sub>F</sub> =20mA
Peak Wavelength	λp			591		nm	
Dominant Wavelength	λd			589		nm	
Spectrum Radiation Bandwidth	Δλ			15		nm	
Forward Voltage	VF		1.7	2.0	2.4	V	
Reverse Current	Ir				10	$\mu$ A	V <sub>R</sub> =5V

\*19-213UYC/S530-XX/TR8



Everlight Electronics Co., Ltd.

Device No:SZDSE-193-027

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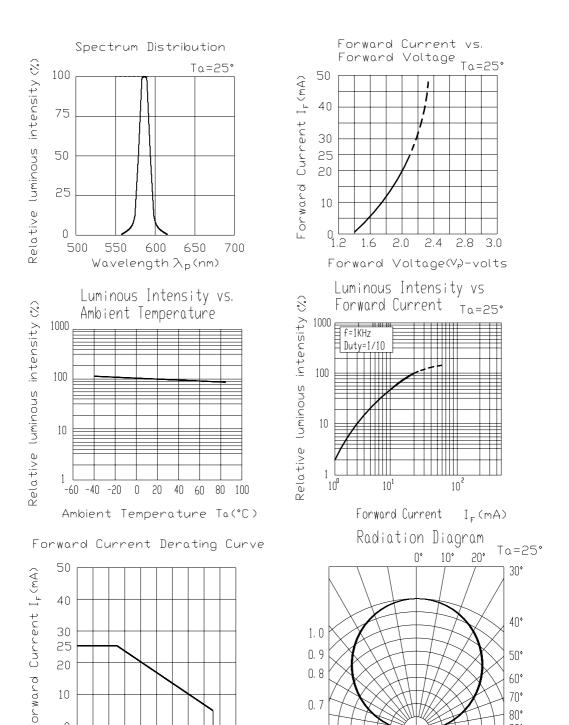
Prepared date:18-Aug-2005

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Prepared by: Wang Zhiyong

#### **Typical Electro-Optical Characteristics Curves**



20

40

60

Ambient Temperature Ta(°C)

85 100

80°

0.7

0.1 0.2 0.4 0.6

### Label explanation

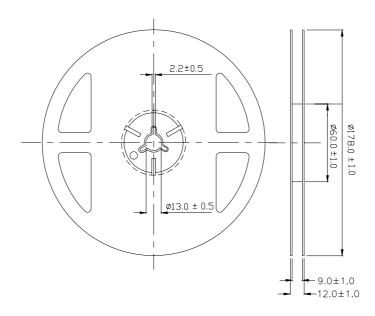
**CAT: Luminous Intensity Rank** 

**HUE: Dom. Wavelength Rank** 

**REF: Forward Voltage Rank** 

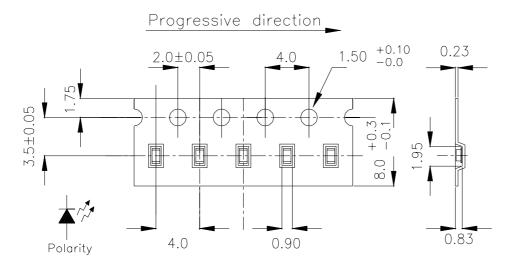


#### **Reel Dimensions**



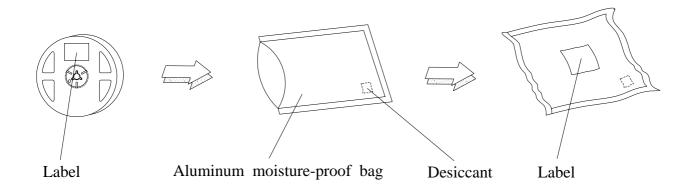
**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm, Unit = mm

#### Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm, Unit = mm

#### **Moisture Resistant Packaging**



#### **Reliability Test Items And Conditions**

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	$H: +100^{\circ}\mathbb{C}$ 15min $\int$ 5 min $L: -40^{\circ}\mathbb{C}$ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H:+100°C 5min  ∫ 10 sec L:-10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°€	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

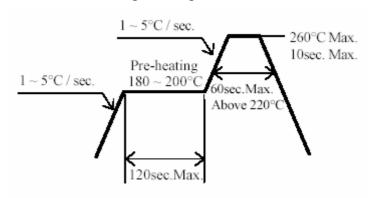
#### **Precautions For Use**

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
  - 2.1 Do not open moisture proof bag before the products are ready to use.
  - 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
  - 2.3 The LEDs should be used within a year.
  - 2.4 After opening the package, the LEDs should be kept at  $30^{\circ}$ C or less and 60%RH or less.
  - 2.5 The LEDs should be used within 168 hours (7 days) after opening the package.
  - 2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

    Baking treatment: 60±5°C for 24 hours.
- 3. Soldering Condition
- 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

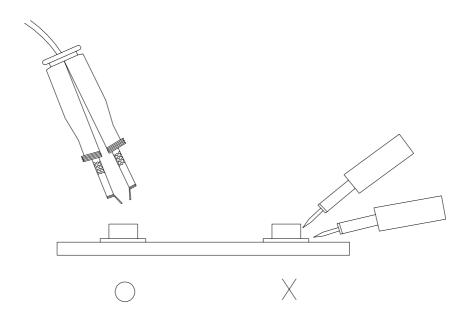


#### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than  $350^{\circ}$ C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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